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NXP USA Inc. - MCR908JK3MDWE Datasheet



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Details

Product Status	Obsolete
Core Processor	HC08
Core Size	8-Bit
Speed	8MHz
Connectivity	-
Peripherals	LED, LVD, POR, PWM
Number of I/O	15
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 12x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SOIC (0.295", 7.50mm Width)
Supplier Device Package	20-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mcr908jk3mdwe

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Technical Data — MC68H(R)C908JL3

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Memory

Addr.	Register Name		Bit 7	6	5	4	3	2	1	Bit 0
	TIM Counter Register	Read:	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8
\$0021	High	Write:								
	(ICNIH)	Reset:	0	0	0	0	0	0	0	0
	TIM Counter Register	Read:	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
\$0022		Write:								
	(ICNIL)	Reset:	0	0	0	0	0	0	0	0
\$0023	TIM Counter Modulo Register High	Read: Write:	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8
	(TMODH)	Reset:	1	1	1	1	1	1	1	1
\$0024	TIM Counter Modulo Register Low	Read: Write:	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
	(TMODL)	Reset:	1	1	1	1	1	1	1	1
	TIM Channel 0 Status and	Read: C	CH0F	CHOIE	MSOR	MSOA	EL SOB	EL SOA	τονο	CHOMAX
\$0025	Control Register	Write:	0	ONDIE	MOOD	MOOA	LLOOD	LLOUA	1000	OT TOWN OV
	(1500)	Reset:	0	0	0	0	0	0	0	0
\$0026	TIM Channel 0 Register High	Read: Write:	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8
	(ICH0H)	Reset:	Indeterminate after reset							
\$0027	TIM Channel 0 Register Low	Read: Write:	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
	(TCH0L)	Reset:	Indeterminate after reset							
	TIM Channel 1 Status and	Read:	CH1F	CH1IF	0	MS1A	FLS1B	FLS1A	TOV1	CH1MAX
\$0028	Control Register	Write:	0	0			22012	220 //		•••••••
	(1501)	Reset:	0	0	0	0	0	0	0	0
\$0029	TIM Channel 1 Register High	Read: Write:	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8
	(TCH1H)	Reset:				Indetermina	te after rese	t		
\$002A	TIM Channel 1 Register Low	Read: Write:	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
	(ICH1L)	Reset:				Indetermina	te after rese	t		
				= Unimple	mented		R	= Reserved	Ł	

Figure 2-2. Control, Status, and Data Registers (Sheet 3 of 5)

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FLASH Memory (FLASH)

4.3 Functional Description

The FLASH memory consists of an array of 4096 or 1536 bytes with an additional 48 bytes for user vectors. The minimum size of FLASH memory that can be erased is 64 bytes; and the maximum size of FLASH memory that can be programmed in a program cycle is 32 bytes (a row). Program and erase operations are facilitated through control bits in the Flash Control Register (FLCR). Details for these operations appear later in this section. The address ranges for the user memory and vectors are:

- \$EC00 \$FBFF; user memory, 4096 bytes: MC68H(R)C908JL3/JK3
- \$F600 \$FBFF; user memory, 1536 bytes: MC68H(R)C908JK1
- \$FFD0 \$FFFF; user interrupt vectors, 48 bytes.
- **NOTE:** An erased bit reads as logic 1 and a programmed bit reads as logic 0. A security feature prevents viewing of the FLASH contents.¹

4.4 FLASH Control Register

The FLASH Control Register controls FLASH program and erase operations.

Address: \$FE08

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	0	0	0	0		MASS	EDAGE	PGM
Write:						IVIAGO	ENAGE	FGIVI
Reset:	0	0	0	0	0	0	0	0



HVEN — High Voltage Enable Bit

This read/write bit enables high voltage from the charge pump to the memory for either program or erase operation. It can only be set if either PGM=1 or ERASE=1 and the proper sequence for program or erase is followed.

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^{1.} No security feature is absolutely secure. However, Freescale's strategy is to make reading or copying the FLASH difficult for unauthorized users.





Figure 6-1. CPU Registers

6.4.1 Accumulator

The accumulator is a general-purpose 8-bit register. The CPU uses the accumulator to hold operands and the results of arithmetic/logic operations.



Figure 6-2. Accumulator (A)



6.6.2 Stop Mode

The STOP instruction:

- Clears the interrupt mask (I bit) in the condition code register, enabling external interrupts. After exit from stop mode by external interrupt, the I bit remains clear. After exit by reset, the I bit is set.
- Disables the CPU clock

After exiting stop mode, the CPU clock begins running after the oscillator stabilization delay.

6.7 CPU During Break Interrupts

If a break module is present on the MCU, the CPU starts a break interrupt by:

- Loading the instruction register with the SWI instruction
- Loading the program counter with \$FFFC:\$FFFD or with \$FEFC:\$FEFD in monitor mode

The break interrupt begins after completion of the CPU instruction in progress. If the break address register match occurs on the last cycle of a CPU instruction, the break interrupt begins immediately.

A return-from-interrupt instruction (RTI) in the break routine ends the break interrupt and returns the MCU to normal operation if the break interrupt has been deasserted.

6.8 Instruction Set Summary

6.9 Opcode Map

See Table 6-2.

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Source	Operation	Description	Effect or CCR						ess e	ode	and	es
Form			۷	н	I	N	z	C Addi		Opc	Opei	Cycl
LSR opr LSRA LSRX LSR opr,X LSR ,X LSR opr,SP	Logical Shift Right	0 → C b7 b0	\$	_	_	0	€	€	DIR INH INH IX1 IX SP1	34 44 54 64 74 9E64	dd ff ff	4 1 4 3 5
MOV opr,opr MOV opr,X+ MOV #opr,opr MOV X+,opr	Move	$(M)_{\text{Destination}} \leftarrow (M)_{\text{Source}}$ $H:X \leftarrow (H:X) + 1 \text{ (IX+D, DIX+)}$	0	-	-	¢	¢	_	DD DIX+ IMD IX+D	4E 5E 6E 7E	dd dd dd ii dd dd	5 4 4 4
MUL	Unsigned multiply	$X:A \leftarrow (X) \times (A)$	-	0	-	-	-	0	INH	42		5
NEG opr NEGA NEGX NEG opr,X NEG ,X NEG opr,SP	Negate (Two's Complement)	$\begin{split} M &\leftarrow -(M) = \$00 - (M) \\ A &\leftarrow -(A) = \$00 - (A) \\ X &\leftarrow -(X) = \$00 - (X) \\ M &\leftarrow -(M) = \$00 - (M) \\ M &\leftarrow -(M) = \$00 - (M) \end{split}$	\$	-	_	⊅	¢	⊅	DIR INH INH IX1 IX SP1	30 40 50 60 70 9E60	dd ff ff	4 1 4 3 5
NOP	No Operation	None	-	-	_	-	-	-	INH	9D		1
NSA	Nibble Swap A	A ← (A[3:0]:A[7:4])	-	-	Ι	-	-	-	INH	62		3
ORA #opr ORA opr ORA opr ORA opr,X ORA opr,X ORA ,X ORA opr,SP ORA opr,SP	Inclusive OR A and M	A ← (A) (M)	0	_	_	\$	¢	_	IMM DIR EXT IX2 IX1 IX SP1 SP2	AA BA CA DA EA FA 9EEA 9EDA	ii dd hh II ee ff ff ee ff	2 3 4 3 2 4 5
PSHA	Push A onto Stack	Push (A); SP \leftarrow (SP) – 1	-	-	-	-	-	-	INH	87		2
PSHH	Push H onto Stack	Push (H); SP \leftarrow (SP) – 1	-	-	-	-	-	-	INH	8B		2
PSHX	Push X onto Stack	Push (X); SP \leftarrow (SP) – 1	-	-	-	-	-	-	INH	89		2
PULA	Pull A from Stack	$SP \leftarrow (SP + 1); Pull(A)$	-	-	-	-	-	-	INH	86		2
PULH	Pull H from Stack	$SP \leftarrow (SP + 1); Pull(H)$	-	-	-	-	-	-	INH	8A		2
PULX	Pull X from Stack	$SP \leftarrow (SP + 1); Pull(X)$	-	-	-	-	-	-	INH	88		2
ROL <i>opr</i> ROLA ROLX ROL <i>opr</i> ,X ROL ,X ROL <i>opr</i> ,SP	Rotate Left through Carry	C d b7 b0	\$	-	_	\$	¢	¢	DIR INH INH IX1 IX SP1	39 49 59 69 79 9E69	dd ff ff	4 1 4 3 5

Table 6-1. Instruction Set Summary





Figure 7-19. Stop Mode Recovery from Interrupt or Break

7.8 SIM Registers

The SIM has three memory mapped registers. **Table 7-4** shows the mapping of these registers.

Table 7-4. SIM Registers	
--------------------------	--

Address	Register	Access Mode				
\$FE00	BSR	User				
\$FE01	RSR	User				
\$FE03	BFCR	User				

7.8.1 Break Status Register (BSR)

The break status register contains a flag to indicate that a break caused an exit from stop or wait mode.



Monitor ROM (MON)

9.4.1 Entering Monitor Mode

Table 9-1 shows the pin conditions for entering monitor mode. As specified in the table, monitor mode may be entered after a POR and will allow communication at 9600 baud provided one of the following sets of conditions is met:

- 1. If $\overline{IRQ1} = V_{DD} + V_{HI}$:
 - External clock on OSC1 is 4.9125MHz
 - PTB3 = low
- 2. If $\overline{IRQ1} = V_{DD} + V_{HI}$:
 - External clock on OSC1 is 9.8304MHz
 - PTB3 = high
- 3. If \$FFFE & \$FFFF is blank (contains \$FF):
 - The oscillator clock is 9.8304MHz (X-tal or RC)
 - IRQ1 = V_{DD}

Table 9-1. Monitor Mode Entry Requirements and Options

IRQ1	\$FFFE and \$FFFF	PTB3	PTB2	PTB1	PTB0	Clock Source and Frequency	Bus Frequency	Comments			
$V_{DD} + V_{HI}$	х	0	0	1	1	OSC1 at 4.9152MHz	2.4576MHz	Bypasses X-tal or RC oscillator; external clock			
V _{DD} + V _{HI}	х	1	0	1	1	OSC1 at 9.8304MHz	2.4576MHz	on PTB0. COP disabled.			
V _{DD}	BLANK (contain \$FF)	x	x	x	1	X-tal or RC oscillator at 9.8304MHz	2.4576MHz	Low-voltage entry to monitor mode. 9600 baud communication on PTB0. COP disabled.			
V _{DD}	NOT BLANK	x	x	x	x	X-tal or RC oscillator at desired frequency	XTALCLK ÷ 4 or RCCLK ÷ 4	Enters User mode. If \$FFFE and \$FFFF is blank, MCU will encounter an illegal address reset.			

Notes:

1. PTB3 = 0: Bypasses the divide-by-two prescaler to SIM when using V_{DD} + V_{HI} for monitor mode entry.

The OSC1 clock must be 50% duty cycle for this condition.

2. XTALCLK is the X-tal oscillator output, for MC68HC908xxx. See Figure 8-1.

4. RCCLK is the RC oscillator output, for MC68HRC908xxx. See Figure 8-2.

5. See Table 18-4 for V_{DD} + V_{HI} voltage level requirements.

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Figure 10-2. TIM I/O Register Summary

10.5.1 TIM Counter Prescaler

The TIM clock source is one of the seven prescaler outputs. The prescaler generates seven clock rates from the internal bus clock. The prescaler select bits, PS[2:0], in the TIM status and control register (TSC) select the TIM clock source.

10.5.2 Input Capture

With the input capture function, the TIM can capture the time at which an external event occurs. When an active edge occurs on the pin of an input capture channel, the TIM latches the contents of the TIM counter into the TIM channel registers, TCHxH:TCHxL. The polarity of the active edge is programmable. Input captures can generate TIM CPU interrupt requests.

10.5.3 Output Compare

With the output compare function, the TIM can generate a periodic pulse with a programmable polarity, duration, and frequency. When the counter reaches the value in the registers of an output compare channel, the TIM can set, clear, or toggle the channel pin. Output compares can generate TIM CPU interrupt requests.

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Timer Interface Module (TIM)



Figure 10-3. PWM Period and Pulse Width

The value in the TIM counter modulo registers and the selected prescaler output determines the frequency of the PWM output. The frequency of an 8-bit PWM signal is variable in 256 increments. Writing \$00FF (255) to the TIM counter modulo registers produces a PWM period of 256 times the internal bus clock period if the prescaler select value is 000 (see 10.10.1 TIM Status and Control Register (TSC)).

The value in the TIM channel registers determines the pulse width of the PWM output. The pulse width of an 8-bit PWM signal is variable in 256 increments. Writing \$0080 (128) to the TIM channel registers produces a duty cycle of 128/256 or 50%.

10.5.4.1 Unbuffered PWM Signal Generation

Any output compare channel can generate unbuffered PWM pulses as described in **10.5.4 Pulse Width Modulation (PWM)**. The pulses are unbuffered because changing the pulse width requires writing the new pulse width value over the old value currently in the TIM channel registers.

An unsynchronized write to the TIM channel registers to change a pulse width value could cause incorrect operation for up to two PWM periods. For example, writing a new value before the counter reaches the old value but after the counter reaches the new value prevents any compare during that PWM period. Also, using a TIM overflow interrupt routine to

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If TIM functions are not required during wait mode, reduce power consumption by stopping the TIM before executing the WAIT instruction.

10.8 TIM During Break Interrupts

A break interrupt stops the TIM counter.

The system integration module (SIM) controls whether status bits in other modules can be cleared during the break state. The BCFE bit in the break flag control register (BFCR) enables software to clear status bits during the break state. (See **7.8.3 Break Flag Control Register** (BFCR).)

To allow software to clear status bits during a break interrupt, write a logic one to the BCFE bit. If a status bit is cleared during the break state, it remains cleared when the MCU exits the break state.

To protect status bits during the break state, write a logic zero to the BCFE bit. With BCFE at logic zero (its default state), software can read and write I/O registers during the break state without affecting status bits. Some status bits have a two-step read/write clearing procedure. If software does the first step on such a bit before the break, the bit cannot change during the break state as long as BCFE is at logic zero. After the break, doing the second step clears the status bit.

10.9 I/O Signals

Port D shares two of its pins with the TIM. The two TIM channel I/O pins are PTD4/TCH0 and PTD5/TCH1.

Each channel I/O pin is programmable independently as an input capture pin or an output compare pin. PTD4/TCH0 can be configured as a buffered output compare or buffered PWM pin.

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Address:	\$0026	TCH0H						
	Bit 7	6	5	4	3	2	1	Bit 0
Read:	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8
Write:								
Reset:			I	Indeterminat	te after reset	t		
Address:	\$0027	TCH0L						
	Bit 7	6	5	4	3	2	1	Bit 0
Read:	D:+7	Dite	Ditc	Di+4	Di+2	Di+0	Di+1	D:+0
Write:	DILI	DILO	DILO	DII4	DILO	DILZ	DILI	DIU
Reset:		•		Indeterminat	te after rese	t		
Address:	\$0029	TCH1H						
	Bit 7	6	5	4	3	2	1	Bit 0
Read:	D'14 5		Disto	Disto	Dista	Bildo	Billo	Die
Write:	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8
Reset:				Indeterminat	te after rese	t		
Address:	\$02A	TCH1L						
	Bit 7	6	5	4	3	2	1	Bit 0
Read:	D147	D:+0	Dhe	DHA	D:10	D:+0	Diad	D:40
Write:	BI[/	ΒΙίρ	BID	BI[4	BII3	BILZ	BILI	BIU
Reset:		1	·	Indeterminat	te after rese	t		

Figure 10-9. TIM Channel Registers (TCH0H/L:TCH1H/L)



Analog-to-Digital Converter (ADC)

11.3 Features

Features of the ADC module include:

- 12 channels with multiplexed input
- Linear successive approximation with monotonicity
- 8-bit resolution
- Single or continuous conversion
- Conversion complete flag or conversion complete interrupt
- Selectable ADC clock

Addr.	Register Name		Bit 7	6	5	4	3	2	1	Bit 0
\$003C	ADC Status and Control Register (ADSCR)	Read:	COCO	AIEN	ADCO	CH4	CH3	CH2	CH1	CH0
		Write:								
		Reset:	0	0	0	1	1	1	1	1
\$003D	ADC Data Register (ADR)	Read:	AD7	AD6	AD5	AD4	AD3	AD2	AD1	AD0
		Write:								
		Reset:	Indeterminate after reset							
\$003E	ADC Input Clock Register (ADICLK)	Read:				0	0	0	0	0
		Write:	ADIVZ	ADIVI ADIVO						
		Reset:	0	0	0	0	0	0	0	0

Figure 11-1. ADC I/O Register Summary

11.4 Functional Description

Twelve ADC channels are available for sampling external sources at pins PTB0–PTB7 and PTD0–PTD3. An analog multiplexer allows the single ADC converter to select one of the 12 ADC channels as ADC voltage input (ADCVIN). ADCVIN is converted by the successive approximation register-based counters. The ADC resolution is 8 bits. When the conversion is completed, ADC puts the result in the ADC data register and sets a flag or generates an interrupt. **Figure 11-2** shows a block diagram of the ADC.

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Address:	\$003D									
	Bit 7	6	5	4	3	2	1	Bit 0		
Read:	AD7	AD6	AD5	AD4	AD3	AD2	AD1	AD0		
Write:										
Reset:	Reset: Indeterminate after reset									
	= Unimplemented									
	Figure 11-4. ADC Data Register (ADR)									

11.8.3 ADC Input Clock Register

This register selects the clock frequency for the ADC.





ADIV2:ADIV0 — ADC Clock Prescaler Bits

ADIV2, ADIV1, and ADIV0 form a 3-bit field which selects the divide ratio used by the ADC to generate the internal ADC clock. **Table 11-2** shows the available clock configurations. The ADC clock should be set to approximately 1MHz.

External Interrupt (IRQ)

13.4 Functional Description

A logic zero applied to the external interrupt pin can latch a CPU interrupt request. **Figure 13-1** shows the structure of the IRQ module.

Interrupt signals on the $\overline{IRQ1}$ pin are latched into the IRQ1 latch. An interrupt latch remains set until one of the following actions occurs:

- Vector fetch A vector fetch automatically generates an interrupt acknowledge signal that clears the IRQ latch.
- Software clear Software can clear the interrupt latch by writing to the acknowledge bit in the interrupt status and control register (ISCR). Writing a logic one to the ACK1 bit clears the IRQ1 latch.
- Reset A reset automatically clears the interrupt latch.

The external interrupt pin is falling-edge-triggered and is softwareconfigurable to be either falling-edge or falling-edge and low-leveltriggered. The MODE1 bit in the ISCR controls the triggering sensitivity of the IRQ1 pin.

When the interrupt pin is edge-triggered only, the CPU interrupt request remains set until a vector fetch, software clear, or reset occurs.

When the interrupt pin is both falling-edge and low-level-triggered, the CPU interrupt request remains set until both of the following occur:

- Vector fetch or software clear
- Return of the interrupt pin to logic one

The vector fetch or software clear may occur before or after the interrupt pin returns to logic one. As long as the pin is low, the interrupt request remains pending. A reset will clear the latch and the MODE1 control bit, thereby clearing the interrupt even if the pin stays low.

When set, the IMASK1 bit in the ISCR mask all external interrupt requests. A latched interrupt request is not presented to the interrupt priority logic unless the IMASK1 bit is clear.

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Keyboard Interrupt Module (KBI)

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Computer Operating Properly (COP)

15.4.5 Reset Vector Fetch

A reset vector fetch occurs when the vector address appears on the data bus. A reset vector fetch clears the SIM counter.

15.4.6 COPD (COP Disable)

The COPD signal reflects the state of the COP disable bit (COPD) in the configuration register (CONFIG). (See Section 5. Configuration Register (CONFIG).)

15.4.7 COPRS (COP Rate Select)

Address:

\$001F

The COPRS signal reflects the state of the COP rate select bit (COPRS) in the configuration register 1.

	Bit 7	6	5	4	3	2	1	Bit 0
Read: Write:	COPRS	R	R	LVID	R	SSREC	STOP	COPD
Reset:	0	0	0	0	0	0	0	0
	R	= Reserved	ł					



COPRS — COP Rate Select Bit

COPRS selects the COP timeout period. Reset clears COPRS.

- 1 = COP timeout period is $(2^{13} 2^4) \times 20$ SCOUT cycles
- 0 = COP timeout period is $(2^{18} 2^4) \times 2OSCOUT$ cycles

COPD — COP Disable Bit

COPD disables the COP module.

- 1 = COP module disabled
- 0 = COP module enabled

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SBSW - SIM Break Stop/Wait

This status bit is useful in applications requiring a return to wait or stop mode after exiting from a break interrupt. Clear SBSW by writing a logic zero to it. Reset clears SBSW.

1 = Stop mode or wait mode was exited by break interrupt

0 = Stop mode or wait mode was not exited by break interrupt

SBSW can be read within the break state SWI routine. The user can modify the return address on the stack by subtracting one from it. The following code is an example of this. Writing zero to the SBSW bit clears it.

; ;	; This code works if the H register has been pushed onto the stack in the break ; service routine software. This code should be executed at the end of the								
;	; break service routine software.								
	HIBYTE	EQU	5						
	LOBYTE	EQU	6						
;		If not	SBSW, do RTI						
		BRCLR	SBSW,BSR, RETURN	; ;	See if wait mode or stop mode was exited by break.				
		TST	LOBYTE, SP	;	If RETURNLO is not zero,				
		BNE	DOLO	;	then just decrement low byte.				
		DEC	HIBYTE, SP	;	Else deal with high byte, too.				
	DOLO	DEC	LOBYTE, SP	;	Point to WAIT/STOP opcode.				
	RETURN	PULH RTI		;	Restore H register.				



18.11 3V Oscillator Characteristics

Table 18-9. Oscillator Component Specifications (3V)

Characteristic	Symbol	Min	Тур	Мах	Unit
Crystal frequency, XTALCLK	f _{OSCXCLK}	—	8	16	MHz
RC oscillator frequency, RCCLK	f _{RCCLK}	2	8	12	MHz
External clock reference frequency ⁽¹⁾	f _{OSCXCLK}	dc	_	16	MHz
Crystal load capacitance ⁽²⁾	CL	—	—	_	
Crystal fixed capacitance ⁽²⁾	C ₁	—	$2 \times C_L$		
Crystal tuning capacitance ⁽²⁾	C ₂	—	$2 \times C_L$	_	
Feedback bias resistor	R _B	—	10 MΩ		
Series resistor ^{(2), (3)}	R _S	—	_		
RC oscillator external R	R _{EXT}	See Figure 18-2			
RC oscillator external C	C _{EXT}		10		pF

NOTES:

No more than 10% duty cycle deviation from 50%
 Consult crystal vendor data sheet

3. Not Required for high frequency crystals



Figure 18-2. RC vs. Frequency (3V @25°C)



19.5 28-Pin PDIP



1. POSITIONAL TOLERANCE OF LEADS (D), SHALL BE WITHIN 0.25 (0.010) AT MAXIMUM MATERIAL CONDITION, IN RELATION TO SEATING PLANE AND EACH OTHER. 2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL. 3. DIMENSION B DOES NOT INCLUDE MOLD FLASH. MILLIMETERS INCHES

NOTES:

DIM	MIN	MAX	MIN	MAX		
Α	36.45	37.21	1.435	1.465		
В	13.72	14.22	0.540	0.560		
С	3.94	5.08	0.155	0.200		
D	0.36	0.56	0.014	0.022		
F	1.02	1.52	0.040	0.060		
G	2.54	BSC	0.10	0 BSC		
Н	1.65	2.16	0.065	0.085		
J	0.20	0.38	0.008	0.015		
K	2.92	3.43	0.115	0.135		
L	15.24	BSC	0.600	BSC		
М	0°	15°	0°	15°		
Ν	0.51	1.02	0.020	0.040		

Figure 19-3. 28-Pin PDIP (Case #710)

19.6 28-Pin SOIC



NOTES:

DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

ANGI T14-3M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER. 3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION. 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) DED SIDE PER SIDE. 5. DIMENSION D DOES NOT INCLUDE DAMBAR

DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INCHES			
DIM	MIN	MAX	MIN	MAX		
Α	17.80	18.05	0.701	0.711		
В	7.40	7.60	0.292	0.299		
С	2.35	2.65	0.093	0.104		
D	0.35	0.49	0.014	0.019		
F	0.41	0.90	0.016	0.035		
G	1.27	BSC	0.050	BSC		
J	0.23	0.32	0.009	0.013		
K	0.13	0.29	0.005	0.011		
М	0°	8°	0°	8°		
Р	10.01	10.55	0.395	0.415		
R	0.25	0.75	0.010	0.029		

Figure 19-4. 28-Pin SOIC (Case #751F)